



# Information & Control North America TC Chapter

## Meeting Summary and Minutes

Standard Fall Meetings  
 Wednesday, November 6, 2024  
 9:00-12:00, 1:00-4:00 PM Pacific Time  
 SEMI HQ, Milpitas

### TC Chapter Announcements

*Next TC Chapter Meeting*

Wednesday, February 26, 2025

9:00-12:00, 1:00-4:00 PM Pacific Time

SEMI HQ, Milpitas

### Table 1 Meeting Attendees

*Italics indicate virtual participants*

**Co-Chairs:** James Moyne (Applied Materials / University of Michigan), Brian Rubow (Cimetrix), Albert Fuchigami (PEER Group)

**SEMI Staff:** Michelle Sun

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
PEER Group Inc.	Fuchigami	Albert	Samsung	<i>Yong</i>	<i>Jae Yong</i>
Cimetrix Incorporated	Rubow	Brian	Applied Materials, Inc.	Moyne	James
Intel Corporation	<i>Maloney</i>	<i>Chris</i>	Applied Materials, Inc.	<i>Perevoztchikov</i>	<i>Konstantin</i>
Arlington Laboratory	<i>Judd</i>	<i>Daniel</i>	SEMI	Sun	Michelle
Agileo Automation	Golra	Fahad	Intel Corp.	<i>Bond</i>	<i>Ryan</i>
ASML Netherlands BV	Horck	van Harold	SCREEN Semiconductor Solutions Co., Ltd.	Nishimura	Takayuki
Doople	Kim	Hyungsu	Hitachi High-Tech Corporation	Toyoshima	Yuko

### Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
ESEC TF	Gerald Shelley (Edwards)	Francesca Dabrowski (Edwards)

### Table 3 TC Chapter Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
None	



**Table 4 Ballot Results**

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
7213	Line Item Revision to SEMI E142-1022 - Specification for Substrate Mapping, SEMI E142.1-0921E — Specification for XML Schema for Substrate Mapping, SEMI E142.2-1016 — Specification for SECS II Protocol for Substrate Mapping, SEMI E142.3-1016 — Specification for Web Services for Substrate Mapping, SEMI E142.4-1022 — Specification for SECS II Protocol for Substrate Mapping Using Item Transfer	
LI-1	Add transfer from (FID) and transfer to (TID) position identifiers	Passed
LI-2	Fix minor editorial errors	Passed
7240A	Revision to SEMI E157-0324, Specification for Module Process Tracking, with title change to: Specification for Module and Substrate Process Tracking	Failed
7241A	New Standard: Guide for Equipment Adoption Criteria for GEM And GEM-Based Standards	Passed
7268	Line Item Revision to SEMI E54.12-1019, Specification for Sensor/Actuator Network Communications For CC-Link®	
LI-1	Replace Biased Terms	Passed
LI-2	Updates to References, Trademarks and Other Editorial Changes	Passed
7269	Line Item Revision to SEMI E54.13-1011 Specification for Sensor/Actuator Network Communications for Ethernet/IP	
LI-1	Replace Biased Terms	Passed
LI-2	Add Mappings for Specific Device Models	Passed
LI-3	Updates to References, Trademarks and Other Editorial Changes	Passed with editorial changes
LI-4	Correct missing SAC Services and mislabeled tables	Passed
7275	Line Item Revision to SEMI E5-0224 - Specification for SEMI Equipment Communications Standard 2 Message Content (SECS-II)	
LI-1	Add Well-Known Names to SEMI E5 items	Failed
7276	Line Item Revision to SEMI E30-0224 - Specification for the Generic Model for Communications and Control of Manufacturing Equipment (GEM)	
LI-1	Correct issues raised by Task Force members	Passed
LI-2	Eliminate ‘must’ terminology	Passed
7278	Line Item Revision to SEMI E90-0624, Specification for Substrate Tracking and SEMI E90.1-0624, Specification for SECS-II Protocol Substrate Tracking	
LI-1	Correct issues with SEMI E90 variables	Passed
7279	Line Item Revision to SEMI E172-1023 - Specification for SECS Equipment Data Dictionary (SEDD)	
LI-1	Add equipment characterization matrix	Passed
LI-2	Eliminate ‘must’ terminology	Passed
7288	Line Item Revision to SEMI E120-0922 (Reapproved 0823) Specification for the Common Equipment Model (CEM), SEMI E120.2-0823 Specification for Protocol Buffers for Common Equipment Model (CEM), SEMI E125-0923, Specification for Equipment Self Description (EqSD) and SEMI E125.2-0923 Specification for Protocol Buffers for Equipment Self Description (EqSD), SEMI E132-0624 Specification for Equipment Client Authentication and Authorization, SEMI E132.2-0624 Specification for Protocol Buffers for Equipment Client	



**Table 4 Ballot Results**

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
	Authentication and Authorization (ECA), SEMI E134-0624 Specification for Data Collection Management, SEMI E134.2-0624 Specification for Protocol Buffers of Data Collection Management, SEMI E179-0624 Specification for Protocol Buffers Common Components	
LI-1	Update issues raised by TF members and rework .proto files to better align with Protocol Buffers Style Guide	Passed with editorial changes
7289	Line Item Revision to SEMI E87-0524 - Specification for Carrier Management (CMS) and SEMI E87.1-0524 Specification for SECS-II Protocol for Carrier Management (CMS)	
LI-1	Correct issues with SEMI E87 variables	Passed
LI-2	Eliminate 'must' terminology	Passed
LI-3	Clarify Carrier State Model Transition #7 trigger	Passed

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

**Table 5 Ratification Ballot Results**

<i>Document #</i>	<i>Document Title</i>	<i>ISC A&amp;R Action</i>
R7068A	New Standard: Specification for Equipment Data Publication	Passed
R7069A	Revision to Add a New Subordinate Standard: Specification for Common Data for Etch Components to Specification for Equipment Data Publication	Passed
R7230	New Standard: Specification for Computing Device Cybersecurity Status Reporting	Passed
R7232	Revision to Add a New Subordinate Standard: Specification for SECS-II Protocol for Computing Device Cybersecurity Status Reporting to Specification for Computing Device Cybersecurity Status Reporting	Passed

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

**Table 6 Activities Approved by the GCS between meetings of the TC Chapter**

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
7288	SNARF Approval	DDA TF	Line Item Revision to SEMI E120-0922 (Reapproved 0823) Specification for the Common Equipment Model (CEM), SEMI E120.2-0823 Specification for Protocol Buffers for Common Equipment Model (CEM), SEMI E125-0923, Specification for Equipment Self Description (EqSD) and SEMI E125.2-0923 Specification for Protocol Buffers for Equipment Self Description (EqSD), SEMI E132-0624 Specification for Equipment Client Authentication and Authorization, SEMI E132.2-0624 Specification for Protocol Buffers for Equipment Client Authentication and Authorization (ECA), SEMI E134-0624 Specification for Data Collection Management, SEMI E134.2-0624 Specification for Protocol Buffers of Data Collection Management, SEMI E179-0624 Specification for Protocol Buffers Common Components



**Table 7 Authorized Activities**

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	Type	SC/TF/WG	Details
7311	SNARF	CDS TF	Line Item Revision to SEMI E191-1024 - Specification for Computing Device Cybersecurity Status Reporting and E191.1-1024 - Specification for SECS-II Protocol for Computing Device Cybersecurity Status Reporting
7312	SNARF	GEM300 TF	Line Item Revision to SEMI E5-0224 - Specification for SEMI Equipment Communications Standard 2 Message Content (SECS-II), and SEMI E30-0224 - Specification for the Generic Model for Communications and Control of Manufacturing Equipment (GEM)

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

**Table 8 Authorized Ballots**

#	When	TF	Details
6743C	Cycle 1-2025	GUI TF	Revision to SEMI E95-1101, Specification for Human Interface for Semiconductor Manufacturing Equipment
6926	Cycle 1-2025	CDS TF	New Standard: Specification for Equipment Operator Access Management and Monitoring
7178	Cycle 1-2025	DDA TF	Revision to SEMI E164-0414 (Reapproved 0721), Specification for EDA Common Metadata
7179	Cycle 1-2025	DDA TF	Revision to Add a New Subordinate Standard: Specification for EDA Common Metadata for Generic Model for Communication and Control of Manufacturing Equipment (GEM) to SEMI E164-0414 (Reapproved 0721), Specification for EDA Common Metadata
7180	Cycle 1-2025	DDA TF	Revision to Add a New Subordinate Standard: Specification for EDA Common Metadata for Processing Management to SEMI E164-0414 (Reapproved 0721), Specification for EDA Common Metadata
7187	Cycle 1-2025	ESEC TF	Revision to SEMI E167-1213 - Specification for Equipment Energy Saving Mode Communications (EESM) and SEMI E167.1-1213 - Specification for SECS-II Protocol for Equipment Energy Saving Mode Communications
7240B	Cycle 1-2025	GEM 300 TF	Revision to SEMI E157-0324, Specification for Module Process Tracking, with title change to: Specification for Module and Substrate Process Tracking
7270	Cycle 1-2025	PCS TF	Line Item Revision to SEMI E151-1211 (Reapproved 0517), Guide for Understanding Data Quality
7311	Cycle 1-2025	CDS TF	Line Item Revision to SEMI E191-1024 - Specification for Computing Device Cybersecurity Status Reporting and E191.1-1024 - Specification for SECS-II Protocol for Computing Device Cybersecurity Status Reporting
7312	Cycle 1-2025	GEM 300 TF	Line Item Revision to SEMI E5-0224 - Specification for SEMI Equipment Communications Standard 2 Message Content (SECS-II), and SEMI E30-0224 - Specification for the Generic Model for Communications and Control of Manufacturing Equipment (GEM)

**Table 9 SNARF(s) Granted a One-Year Extension**

#	TF	Title	Expiration Date
6743	GUI TF	Revision to SEMI E95-1101, Specification for Human Interface for Semiconductor Manufacturing Equipment	11/6/2025



**Table 10 SNARF(s) Cancelled**

#	TF	Title
6722	Sensor Bus TF	Reapproval of SEMI E54.11 - Specification for Sensor/Actuator Network Specific Device Model for Endpoint Devices
6724	Sensor Bus TF	Reapproval of SEMI E54.3 - Specification for Sensor/Actuator Network Specific Device Model for Mass Flow Device
6852	Sensor Bus TF	Reapproval of SEMI E142.3-1016, Specification for Web Services for Substrate Mapping
7227	Sensor Bus TF	Line Item Revision to SEMI E125-0923 Specification for Equipment Self Description (EqSD) and SEMI E125.2-0923 Specification for Protocol Buffers for Equipment Self Description (EqSD)
7275	Sensor Bus TF	Line Item Revision to SEMI E5-0224 - Specification for SEMI Equipment Communications Standard 2 Message Content (SECS-II)

**Table 11 Standard(s) to receive Inactive Status**

Standard Designation	Title
None	

**Table 12 New Action Items**

Item #	Assigned to	Details
1	Ryan Bond	Contact Shuba Viswanath and see if she intends on continuing leading the EDP TF
2	Brian Rubow	Contact Richard Howard and see if she intends on continuing leading the CDS TF
3	SEMI Staff	Fix login for Harold van Horck (ASML), Konstantin Perevoztchikov (AMAT)
4	SEMI Staff	Send out 2-week review for SEMI E90, E90.1 SNARF
5	SEMI Staff	Add Jack Ghiselli as I&C co-chair emeritus

**Table 13 Previous Meeting Action Items**

Item #	Assigned to	Details
None		

**1 Welcome, Reminders, and Introductions**

Albert Fuchigami (PEER Group) called the meeting to order at 9:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

**Attachment:** Required Meeting Elements March 2024

**2 Review of Previous Meeting Minutes**

The TC Chapter reviewed the minutes of the previous meeting.

- Motion:** Approve the minutes as written
- By / 2<sup>nd</sup>:** By: Daniel Judd / Arlington Laboratory  
Second: Takayuki Nishimura / SCREEN
- Discussion:** None
- Vote:** 8-Y 0-N

**Attachment:** IC-Minutes-July-2024

### 3 Liaison Reports

#### 3.1 I&C Japan TC Chapter

Takayuki Nishimura (SCREEN) reported for the I&C Japan TC Chapter. Of note:

- Meeting Schedule
  - o Last Meeting: Friday July 26th, 2024, 11:00-14:30 [JST]
  - o Next Meeting: Friday December 13th, 2024, 13:30-16:30 [JST]
- Leadership Changes
  - o Yuko Toyoshima / Hitachi High-Tech Corporation was appointed as the third I&C co-chair
- Committee Structure Changes
  - o Sensor Bus Task Force has been disbanded
- Ballot Results
  - o Ballot 7173, Line Item Revision to SEMI E30
    - LI 1-5 passed

#### 3.2 I&C Taiwan TC Chapter

Michelle Sun (SEMI) reported for the I&C Taiwan TC Chapter. Of note:

- Last Meeting
  - o October 24, 2024
  - o Hybrid meeting
- CDS Task Force
  - o E187 V2 SNARF in process for two weeks GTC review. (Major revision)
  - o Draft Development → First draft to be available for review by the end of 2024
- New Business
  - o Disbanded GEM300TF, Backend Factory Integration TF, Equipment Information Integration TFs due to no activities. Also, these 2 leaders' job functions have changed.

**Attachment:** IC Taiwan Liaison Report\_20241024\_V1

#### 3.3 SEMI Staff Report

Michelle Sun (SEMI) gave the SEMI Staff Report. Of note:

2024 & 2025 Calendar of Events

- SEMICON Europa – Nov 12-15 in Munich, Germany
- SEMICON Japan – Dec 11-13 in Tokyo, Japan
- SEMICON Korea – Feb 19-21, 2025, in Seoul, Korea
- SEMICON China – March 26-28, 2025, in Shanghai, China
- SEMICON Southeast Asia – May 20-22, 2025, in Singapore

Global Standards Summit @ SEMICON Japan 2024

- **Inaugural SEMI Event @ SEMICON Japan 2024**
  - o Thursday, December 12 | 10:30 AM to 4:30 PM
  - o Tokyo Big Sight, Conference Tower, Room 606
- **Objective:** Identify standards-critical areas and work towards an industry standardization strategy for the next 3- and 7-year time horizons.
- **Session Topics**
  - o Smart Manufacturing for Future Factories
  - o Packaging Architectures & Materials
  - o Environmental Sustainability
- **Why Attend?**
  - o *Learn* – Hear issues critical to the future advancements of semiconductor manufacturing, what's happening to address them, as well as the standards needed to help enable.
  - o *Influence* – Contribute to the direction of standards development by providing inputs to help optimize future factories.



- *Network* – Organized networking events with other stakeholders from suppliers to solution providers to end customers.
- *Discover* – Explore what SEMICON Japan has to offer (e.g., Sessions on AI & Data, Sustainability, Manufacturing, Integration of Front & Back-end; Standards Meetings)

SEMICON West 2025-2030

- **2025—October 7-9 | Phoenix Convention Center | Phoenix, AZ**
- 2026—October 13-15 | Moscone Center | San Francisco, CA
- **2027—October 12-14 | Phoenix Convention Center | Phoenix, AZ**
- 2028—October 10-12 | Moscone Center | San Francisco, CA
- **2029—October 9-11 | Phoenix Convention Center | Phoenix, AZ**
- 2030—October 29-31 | Moscone Center | San Francisco, CA

Upcoming NA Meetings 2025

Event Name	Date/Venue	Ballot Cycles to Consider (refer to next slides for details)
NA Standards Winter Meetings	Feb 24-27, 2025 SEMI HQ, Milpitas, California/USA	Cycle 9-24 • Ballot Submission Date: Friday, November 8, 2024 • Voting Period Starts: Friday, November 22, 2024 • Voting Period Ends: Monday, December 23, 2024 Cycle 1-25 • Ballot Submission Date: Tuesday, December 17, 2024 • Voting Period Starts: Wednesday, January 8, 2025 • Voting Period Ends: Friday, February 7, 2025
NA Standards Summer Meetings	June 2-5, 2025 <i>[Tentative]</i> SEMI HQ, Milpitas, California/USA	Cycle 3-25 • Ballot Submission Date: Wednesday, March 5, 2025 • Voting Period Starts: Wednesday, March 19, 2025 • Voting Period Ends: Friday, April 18, 2025 Cycle 4-25 • Ballot Submission Date: Thursday, March 20, 2025 • Voting Period Starts: Wednesday, April 9, 2025 • Voting Period Ends: Friday, May 9, 2025
SEMICON West	Oct 7-9, 2025 Phoenix Convention Center Phoenix, Arizona/USA	Cycle 6-25 • Ballot Submission Date: Thursday, June 19, 2025 • Voting Period Starts: Wednesday, July 9, 2025 • Voting Period Ends: Friday, August 8, 2025 Cycle 7-25 • Ballot Submission Date: Thursday, July 24, 2025 • Voting Period Starts: Wednesday, August 13, 2025 • Voting Period Ends: Friday, September 12, 2025

Critical Dates for SEMI Standards Ballots – 2025

2025	Ballot Submission Deadline	Voting Opens	Voting Closes
<b>Cycle 1</b>	Dec 17, 2024	January 8	February 7
<b>Cycle 2</b>	January 23	February 11	March 13
<b>Cycle 3</b>	March 5	March 19	April 18
<b>Cycle 4</b>	March 20	April 9	May 9
<b>Cycle 5</b>	May 8	May 28	June 27
<b>Cycle 6</b>	June 19	July 9	August 8
<b>Cycle 7</b>	July 24	August 13	September 12

SEMI Standards Publications

- Total SEMI Standards in portfolio: 1,092
- Includes 349 Inactive Standards

SEMI Standards Publications



Cycle	Designation	Title	Committee	Region
July 2024	SEMI D85	Guide for the Tone Reproduction Curves for Transparent Displays	FPD - Metrology	TW
July 2024	SEMI FH4	Test Method and Guide for the Tactile Characteristics of Flexible Hybrid Electronics Materials and Products	Flexible Hybrid Electronics	JA
October 2024	SEMI E191	Specification for Computing Device Cybersecurity Status Reporting	Information & Control	NA
October 2024	SEMI E191.1	Specification for SECS-II Protocol for Computing Device Cybersecurity Status Reporting to Specification for Computing Device Cybersecurity Status Reporting	Information & Control	NA

#### Regulations Procedure Manual Updates

- Regulations (Feb 20, 2024)
  - New definition of “Standards Document”
  - Clarification of confidential presentation materials
    - <https://www.semi.org/sites/semi.org/files/2024-02/Standards%20Regulations%20February%202024.pdf>
- Procedure Manual (Feb 20, 2024)
  - The use of Connect@SEMI for TF management and document development depository (next slide)
- Procedure Manual (Sept 27, 2024) New!
  - Clarification of § 6.4.5.10 for discharging of a TF
  - New ¶ 6.4.5.11 Designation of a TF as Dormant.
    - <https://www.semi.org/sites/semi.org/files/2024-09/Procedure%20Manual%20September%202024.pdf>

#### Connect@SEMI Communities for all SEMI Standards Task Forces

- By Feb 2025, all Standards Task Forces shall use Connect@SEMI to host documents that are currently in development.
- Each Standards Task Force will have its own Community Page on Connect@SEMI.
- All program members may log in at:
  - <https://connect.semi.org>
  - Enter their username and password (same as program membership log-in)
  - Contact staff if there are any questions.
- Training materials are available at:
  - <https://www.semi.org/standards>
  - Under Standards Developer Resources → Collaboration Tools (scroll to the bottom)

#### SEMIViews 4.0 – Available Now!

- New SEMIViews platform launched on August 19, 2024.
- SEMIViews 4.0 Features include:
  - Upgraded user interface
  - Improved company user administration functions
  - Dynamic landing page, including feeds for new and revised Standards, upcoming meetings & events, and a reference center
  - Enhanced search functionality and navigation panel
  - New SEMI Volumes Library
  - User defined shortcuts via Collections, Favorites, and now, Bookmarks
- Additional features planned in the pipeline.

**Attachment:** Staff Report November 2024 v4



## 4 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

4.1 Document #7213, Line Item Revision to SEMI E142-1022 - Specification for Substrate Mapping, SEMI E142.1-0921E — Specification for XML Schema for Substrate Mapping, SEMI E142.2-1016 — Specification for SECS II Protocol for Substrate Mapping, SEMI E142.3-1016 — Specification for Web Services for Substrate Mapping, SEMI E142.4-1022 — Specification for SECS II Protocol for Substrate Mapping Using Item Transfer

4.1.1 Line Item #1: Add transfer from (FID) and transfer to (TID) position identifiers

4.1.2 Line Item #2: Fix minor editorial errors

**Attachment:** AR - 7213

4.2 Document #7240A, Revision to SEMI E157-0324, Specification for Module Process Tracking, with title change to: Specification for Module and Substrate Process Tracking

**Motion:** This Document failed TC Chapter review and will be returned to the TF for rework.

**By / 2<sup>nd</sup>:** By: Daniel Judd / Arlington Laboratory  
Second: Brian Rubow / Cimatrix Incorporated

**Discussion:** None

**Vote:** 9-Y, 0-N

4.3 Document #7241A, New Standard: Guide for Equipment Adoption Criteria for GEM And GEM-Based Standards

**Motion:** This Document passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review

**By / 2<sup>nd</sup>:** By: Daniel Judd / Arlington Laboratory  
Second: Brian Rubow / Cimatrix Incorporated

**Discussion:** None

**Vote:** 9-Y, 0-N

**Attachment:** AR – 7241A

4.4 Document #7268, Line Item Revision to SEMI E54.12-1019, Specification for Sensor/Actuator Network Communications For CC-Link®

**Motion:** Line item(s) [1], [2] passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review.

**By / 2<sup>nd</sup>:** By: Daniel Judd / Arlington Laboratory  
Second: Brian Rubow / Cimatrix Incorporated

**Discussion:** None

**Vote:** 9-Y, 0-N

**Attachment:** AR – 7268

4.5 Document #7269, Line Item Revision to SEMI E54.13-1011 Specification for Sensor/Actuator Network Communications for Ethernet/IP

**Motion:** Line item(s) [1], [2], [4] passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review.

Line item(s) [3] passed TC Chapter review with editorial changes and will be forwarded to the ISC A&R SC for procedural review.



**By / 2<sup>nd</sup>:** By: Daniel Judd / Arlington Laboratory  
Second: Brian Rubow / Cimatrix Incorporated

**Discussion:** None

**Vote:** 9-Y, 0-N

**Attachment:** AR – 7269

4.6 Document #7275, Line Item Revision to SEMI E5-0224 - Specification for SEMI Equipment Communications Standard 2 Message Content (SECS-II)

**Motion:** This Document failed TC Chapter review and work will be discontinued

**By / 2<sup>nd</sup>:** By: Brian Rubow / Cimatrix Incorporated  
Second: Albert Fuchigami / PEER Group Inc

**Discussion:** None

**Vote:** 10-Y, 0-N

4.7 Document #7276, Line Item Revision to SEMI E30-0224 - Specification for the Generic Model for Communications and Control of Manufacturing Equipment (GEM)

**Motion:** This Document failed TC Chapter review and work will be discontinued

**By / 2<sup>nd</sup>:** By: Brian Rubow / Cimatrix Incorporated  
Second: Albert Fuchigami / PEER Group Inc

**Discussion:** None

**Vote:** 10-Y, 0-N

4.8 Document #7278, Line Item Revision to SEMI E90-0624, Specification for Substrate Tracking and SEMI E90.1-0624, Specification for SECS-II Protocol Substrate Tracking

**Motion:** Line item(s) [1] passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review.

**By / 2<sup>nd</sup>:** By: Brian Rubow / Cimatrix Incorporated  
Second: Fahad Golra / Agileo Automation

**Discussion:** None

**Vote:** 9-Y, 0-N

**Attachment:** AR – 7278

4.9 Document #7279, Line Item Revision to SEMI E172-1023 - Specification for SECS Equipment Data Dictionary (SEDD)

**Motion:** Line item(s) [1], [2] passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review

**By / 2<sup>nd</sup>:** By: Brian Rubow / Cimatrix Incorporated  
Second: Daniel Judd / Arlington Laboratory

**Discussion:** None

**Vote:** 10-Y, 0-N

**Attachment:** AR – 7279

4.10 Document #7288, Line Item Revision to SEMI E120-0922 (Reapproved 0823) Specification for the Common Equipment Model (CEM), SEMI E120.2-0823 Specification for Protocol Buffers for Common Equipment Model (CEM), SEMI E125-0923, Specification for Equipment Self Description (EqSD) and SEMI E125.2-0923



Specification for Protocol Buffers for Equipment Self Description (EqSD), SEMI E132-0624 Specification for Equipment Client Authentication and Authorization, SEMI E132.2-0624 Specification for Protocol Buffers for Equipment Client Authentication and Authorization (ECA), SEMI E134-0624 Specification for Data Collection Management, SEMI E134.2-0624 Specification for Protocol Buffers of Data Collection Management, SEMI E179-0624 Specification for Protocol Buffers Common Components

**Motion:** Line item(s) [1] passed TC Chapter review with editorial changes and will be forwarded to the ISC A&R SC for procedural review  
**By / 2<sup>nd</sup>:** By: Brian Rubow / Cimatrix Incorporated  
Second: Fahad Golra / Agileo Automation  
**Discussion:** None  
**Vote:** 9-Y, 0-N  
**Attachment:** AR – 7288

4.11 Document #7289, Line Item Revision to SEMI E87-0524 - Specification for Carrier Management (CMS) and SEMI E87.1-0524 Specification for SECS-II Protocol for Carrier Management (CMS)

**Motion:** Line item(s) [1], [2], [3] passed TC Chapter review with editorial changes and will be forwarded to the ISC A&R SC for procedural review  
**By / 2<sup>nd</sup>:** By: Brian Rubow / Cimatrix Incorporated  
Second: Takayuki Nishimura / SCREEN Semiconductor Solutions Co., Ltd  
**Discussion:** None  
**Vote:** 9-Y, 0-N  
**Attachment:** AR – 7289

## 5 Subcommittee and Task Force Reports

### 5.1 ABFI Task Force

Brian Rubow (Cimatrix) reported for the ABFI Task Force. Of note:

- SNARF Proposals
  - E90 Line-Item Revision Multiple Substrate Id Reader Support
    - Review then request GCS approval after two-week review
- New Activities
  - Aligning other standards with E142
  - Inspection may be performed on un-patterned wafers.
    - Defect XY coordinates (microns) should be mapped to E142 PhysicalCoordinates
  - Test cells (tester and prober) use their own origin orientation, etc.
    - Device XY coordinates (col, row) should be mapped to E142 LogicalCoordinates
  - Assembly and FT equipment that support mapping should follow E142 SEMI standard

**Attachment:** ABFI TF Meeting\_110424

### 5.2 CDS Task Force

Ryan Bond (Intel) reported for the CDS Task Force. Of note:

- Leadership Changes
  - None



- Ballot Adjudication
  - Ballot 7230: New Standard: Specification for Computing Device Cybersecurity Status Reporting – **Published as SEMI E191-1024**
  - Ballot 7232: Revision to Add a New Subordinate Standard: Specification for SECS-II Protocol for Computing Device Cybersecurity Status Reporting to Specification for Computing Device Cybersecurity Status Reporting - **Published as SEMI E191.1-1024**

**Attachment:** CDS - November 2024 Meeting Slides - AF - Rev 1.1

### 5.3 Sensor Bus Task Force

Dan Judd (Arlington Laboratory) reported for the Sensor Bus Task Force. Of note:

- Doc #7268 – Line Item Revision to Semi E54.12-1019 Specification for Sensor/Actuator Network Communications for CC-Link.
  - Superclean
- Doc #7269 – Line Item Revision to SEMI E54.13-1011 Specification for Sensor/Actuator Network Communications for Ethernet/IP.
  - Negative Withdrawn

**Attachment:** TaskForceReport SensorBus SEMI-NA-Fall2024 v1

### 5.4 EDP Task Force

Of note:

- EDP and Etch subordinate Cycle 5 Ballot submission complete.
  - 7068 & 7069 passed the ballot
  - Discussed Ratification Ballot Results – both passed
  - Proofs are out for review.
- Next Steps
  - Next Level 1 category – Plasma under discussion to define level 2/3.
  - Team decided to look into the Ethercat parameter list for RF. Tools that are not compatible with Ethercat will get the ones defined by Etch subordinate standard.
  - Beginning discussions to kick off the subordinate team for Deposition deep dive.
  - Introduced traceability
  - Semicon Japan 2024, Global
    - Topic 1: Optimizing the semiconductor manufacturing process {70 minutes} - Autonomous fab
    - Topic 2: Packaging Architectures & Materials {70 minutes, 12:45 PM – 1:55 PM}
    - Topic 3: Environmental Sustainability {70 mins}

### 5.5 DDA Task Force

Of note:

- Request Ballot Authorization- Cycle 1 – 2025



- E164 Revision (Ballot 7178)
- New E164 Subordinate Standard for SEMI E30 content (Ballot 7179)
- New E164 Subordinate Standard for SEMI E40 content (Ballot 7180)
- EDA Software Vendor Tests
  - Test Session #3 – Scheduled for Thurs Nov 7th. Focus on interoperability with SEMI E134 functionality.
  - Reviewing issues identified in preparation for and during Test Session #3.
- SEMI E164
  - Active development to rework it for Freeze 3. Creating complementary files using JSONC format.

**Attachment:** DDA TF Report - November 2024\_Rev 1.0

### 5.6 GUI Task Force

Of note:

- Reviewed 6743C draft revision 3.2
- Items discussed in the meeting
  - Ballot reorganization experiment
  - Considering separate LSD and SSD sections – pros and cons
  - Discussed a subordinate standards approach
- Updates to draft in progress
  - Discussed edits to orientation of Navigation Panel as vertical or horizontal
  - Discussed screen ratios in figures
  - Discussed portrait orientation as applies to either LSD and SSD

**Attachment:** GUI TF Report - 2024-11-05

### 5.7 PCS Task Force

Of note:

- **Date and Event**
  - # of attendees in person: 4 (including staff)
  - # of attendees remote/online: 3
- **TF Leadership & changes (if any): None**
- **New SNARFs: None**
- **Ballot Adjudication: None**
- **New business**
  - **Line Item update to SEMI E151-1211, Guide for understanding data quality**
    - Ballot to be generated for review at next meeting
  - **ABFI:** Christian / Infineon is in contact with Albert / PEER Group and will work on a SNARF. After SNARF is developed we can assess where the work should be done.
  - **E133 and Digital Twins**
    - PCS task force (and feedback from NIST and the IMA-APC Council meeting) believes technical definitions for DT and DT framework are a critical first step. PCS TF is going to work to create these standards
    - Paul Trio said SEMI will do what it can to help with the effort and promotion

**Attachment:** PCS-TF-report20241103



5.8 GEM 300 Task Force

Of note:

- Adjudicated Ballots 7275-1, 7276-1, 7276-2, 7278-1, 7279-1, 7279-2, 7289-1, 7289-2, 7289-3, 7240A-1
  - Long discussion regarding ballot 7275-1 and the naming of well-knowns which are defined in E5 and used in other standards. A majority wishes to use an 'E5 prefix', while a minority wishes to use a prefix based on where the standard is used.
- Reviewed E90 SNARF

**Attachment:** SEMI NA-ICC-GEM300-TF Report Fall 2024

5.9 ESEC Task Force

Of note:

- SNARF approved – 7187, Revision to SEMI E167-1213 - Specification for Equipment Energy Saving Mode Communications (EESM) and SEMI E167.1-1213 - Specification for SECS-II Protocol for Equipment Energy Saving Mode Communications
- Discussion
  - Single state model or multiple models: Equipment and process modules
  - Definition for process module numbering systems – Check other SEMI standards
  - Simplification of text, see attached documents, e.g., 7.2.3. and 7.2.4.
  - Delete reference to maintenance case in 7.3.2.2
  - Check SEMI policy on terms, such as “Black box”

**6 Next Meeting and Adjournment**

The next meeting is scheduled for Wednesday, February 26, 2025, at SEMI HQ, Milpitas. See <http://www.semi.org/standards-events> for the current list of events.

Adjournment: 2:45

Respectfully submitted by:

Michelle Sun  
 Coordinator  
 SEMI North America  
 Email: [msun@semi.org](mailto:msun@semi.org)

Minutes tentatively approved by:

<Name> (<Company>), Co-chair	<Date approved>
<Name> (<Company>), Co-chair	<Date approved>

**Table 14 Index of Available Attachments#1**

<i>Title</i>	<i>Title</i>
Required Meeting Elements March 2024	AR – 7268
IC-Minutes-July-2024	AR – 7269
IC Taiwan Liaison Report_20241024_V1	AR – 7278
Staff Report November 2024 v4	AR – 7279



**Table 14 Index of Available Attachments#1**

AR - 7213	7288
AR – 7241A	7289
ABFI TF Meeting_110424	GUI TF Report - 2024-11-05
CDS - November 2024 Meeting Slides - AF - Rev 1.1	PCS-TF-report20241103
TaskForceReport SensorBus SEMI-NA-Fall2024 v1	SEMI NA-ICC-GEM300-TF Report Fall 2024
DDA TF Report - November 2024_Rev 1.0	Staff Report November 2024 v4
IC Taiwan Liaison Report_20241024_V1	

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at [www.semi.org](http://www.semi.org). For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.